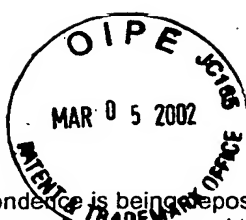


Docket No.: 1999P1711



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Date: February 25, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Jörg-Erich Sorg
Applic. No. : 10/007,398
Filed : October 22, 2001
Title : LED Light Source with Lens and Corresponding Production Method
Art Unit : 2879

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

United States Patent No. 3,875,456 (Kano et al.), dated April 1, 1975;

United States Patent No. 5,043,716 (Latz et al.), dated August 27, 1991;

United States Patent No. 5,847,507 (Butterworth et al.), dated December 8, 1998;

German Published, Non-Prosecuted Patent Application DE 196 38 667 A1 (Schlotter et al.), dated April 2, 1998, mixed colored light emitting semiconductor component with light emitting conversion element;

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European Patent Application EP 0 230 336 A1 (Thillays), dated July 29, 1987, surface mounted opto-electronic device;

European Patent Application EP 0 854 523 A2 (Oshio et al.), dated July 22, 1998;

International Publication WO 83/00408 (Sieg), dated February 3, 1983;

Japanese Patent Abstract JP 62-196878 (A) (Masaru), dated August 31, 1987;

Japanese Patent Abstract JP 10 065 221 A (Matoba et al.), dated March 6, 1998;

Japanese Patent Abstract JP 10 188 649 A (Hase), dated July 21, 1998;

Willy Reisen: "Lumineszenz-Dioden - die Leuchtmittel von morgen?" [light emitting diodes - the light source of the future?], Licht, 4/98, pp. 302-304;


Frank Möllmer et al.: „Siemens SMT-TOPLED für die Oberflächenmontage, “ [Siemens SMT-TOPLED for surface mounting], Siemens Components, Vol. 29, 1991, No. 4, pp. 147-149;

Frank Möllmer et al.: „Siemens SMT-TOPLED für die Oberflächenmontage, “ [Siemens SMT-TOPLED for surface mounting], Siemens Components, Vol. 29, 1991, No. 5, pp. 193-196.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications,

patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicant

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